

### Silicon precision timing detectors

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### Fermilab U.S. DEPARTMENT OF Office of Science



# Precision timing: why do we need it?

- But... mostly blind to time structure within each bunch crossing.
- LHC proton bunches cross every 25 ns, lasting 0.5 ns each crossing. • Detector readout repeats at 25 ns (40 MHz)—very fast!



(N.B. real collisions aren't spherically symmetric!)

Collision structure at an LHC detector



# Precision timing: why do we need it?

- Each bunch crossing: tons of simultaneous pileup interactions!
  - **Typical mean # of PU interactions:** • LHC: 20-50 • High-Lumi LHC: 200
  - Future hadron collider: 1000 (!)
- High Lumi LHC: events too dense / complex to reconstruct accurately
- Precision timing can provide simplification!









### **Precision timing for CMS in HL-LHC era** Separate spatially overlapping vertices with intra-bunch time information



- Install in advance of HL-LHC.

### MIP Timing Detector (MTD): timestamp every track with 30-60 ps resolution





# Impact of timing on CMS performance

- Reduce effective pileup to current levels: maintain core physics performance Time of Flight identification for soft hadrons
- New discovery capability for exotic long-lived & slow moving particles







### LGAD sensors

- Endcap region near beamline: high radiation tolerance required
- - Thin depletion region (50 micron): fast & uniform signals
  - Internal gain: boost signal-to-noise (x10-30)



# • Silicon sensors optimized for timing: Low Gain Avalanche Detectors (LGADs) Endcap timing layer









## Ingredients to time resolution in silicon sensors

- Measuring time of arrival: look for signal to cross threshold.
- Main contributions to resolution:
  - Jitter the impact of noise

$$\sigma_{\text{jitter}} = \frac{t_{\text{rise}}}{S/N} = \frac{N}{dV/dt}$$

Maximize signal: add internal gain Minimize risetime: THIN sensors (50  $\mu$ m) N  $V_{N}$ dV/dt(3-3)







### Ingredients to time resolution in silicon sensors

- Measuring time of arrival: look for signal to cross threshold.
- Main contributions to resolution:
  - Jitter the impact of noise
  - Signal variations fluctuations in deposited charge
    - "Time walk": variation in TOTAL charge (Q)

Time walk on threshold crossing:



Easily corrected with measurement of total.

Figure 10 Left side: Signals of different ampl



# Ingredients to time resolution in silicon sensors

- Measuring time of arrival: look for signal to cross threshold.



### **Sensor time resolution**



### Depends on thickness: 30 ps for 50 µm

Depends on gain, thickness, noise: ~ 10 ps



### Full detector resolution



### Full ETL system: possible to achieve ~35 ps resolution per hit!

Good references: Cartiglia, Hadrozinski, Seiden: <u>arxiv:1704.08666</u> W. Riegler and G. Aglieri Rinella <u>2017 JINST 12 P11017</u>

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### HPK LGAD prototype, 1.3 mm pad



### What does it take to scale from 1 mm<sup>2</sup> to 14 m<sup>2</sup>?

### Endcap timing layer, 2.6 m







# How do we study LGADs?

### Best playground for collider detector: test beam



- 120 GeV proton beam as proxy for particles in CMS

Telescope by L. Uplegger et al. (UniMi alum) Key LGAD questions: uniformity in large sensors; radiation hardness (up to 1.5x10<sup>15</sup> neq /cm<sup>2)</sup>







### Test

- For e
  - Arriv
  - Impa







### Measure proton trajectory with tracker



### The team at work!











# **Key questions for LGADs**

- Uniformity—
  - Large areas of detector ( $\geq 4x4$  cm<sup>2</sup>) constrained to same bias voltage
  - If gain implant is not uniform—can't operate successfully.
- Early on, noticed sensors with rather severe gradients:



Critical need to improve gain uniformity!



# **Demonstrating uniformity**

- Over time, iterated with foundries to improve uniformity
- In parallel, developed strategy to verify uniformity with simple probe tests

### Latest sensor production: good uniformity



### improve uniformity rify uniformity with simple probe tests



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### Correlate probe measurements (passive) with gain (active)



### LGAD radiation hardness

- Gain implant de-activates with irradiation at LHC
- Emulate by exposure at nuclear reactor (up to 1.5 x 10<sup>15</sup> neq / cm<sup>2</sup>)

Hamamatsu LGAD prototypes (beta source)



Compensate by increasing bias.





### LGAD radiation hardness

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Hamamatsu LGAD prototypes (beta source) Split 1 pre-rad ♦ Split 1, 8e14 ∮ Split 1, 1.5e15 50



Compensate by increasing bias.



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# LGAD radiation hardness

- Market survey underway—studying prototypes from several vendors.
- - FBK and IHEP-IME



- Best designs keep 30-40 ps resolution at end of life, with bias < 550 V
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# Co-implantation of carbon yields significantly improved radiation hardness



### LGAD mortality



- Several test beam campaigns dedicated to study of LGAD mortality
  - Controlled death (30 sensors) → understand death mechanism
  - Survival demonstration (20 sensors) → prove safe mitigation

• Anecdotally, noticed death of highly irradiated LGADs at test beams, at very high field. - Historically, not clear if caused by environmental/mishandling issue, or intrinsic sensor failure.





## **Controlled death studies with test beam**

- Measure beam profile with tracker.
- Align each sensor with beam based on single-ch readout.
- Carefully increase bias voltage
  - ~3k protons on sensor per minute. Raise bias 25V after 100-200k protons.



### Beam profile

Single pad hit efficiency

Most sensors in 2x2 geometry Most from Hamamatsu







# **Example burnout event**

### Hamamatsu 1.5e15 neq/cm<sup>2</sup>



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- When death occurs, first observe short on bias supply
- Then, find LGAD waveform indicating moment of death
- Compare track position in fatal event with crater location.











### Example burnout event

### Hamamatsu 1.5e15 neq/cm<sup>2</sup>



### Burnout is decisively caused by proton!



### Burnout in PIN diode—no gain. Gamma-irradiated HPK PIN diode (50 micron)









### **Conclusions from initial burnout studies**

- All 50 micron sensors susceptible to death at bias  $\geq$  600 V - Gain, fluence not relevant for death mechanism. - Susceptibility depends on voltage & thickness ONLY
- Suspected mechanism, "Single Event Burnout" (SEB) - Rare, extremely high ionization events with energy deposit > 50-100 MeV - Excess charge produces narrow conductive path across diode at extreme field: burnout
- - due to high current density.
- Hint towards mitigation strategy: safe below  $\sim 11-12$  V / micron.





### Survival demonstration

- Initial survival demonstration: ~10<sup>9</sup> protons, no deaths.
- But, CMS flux is 10<sup>12-13</sup> charged particles / year / sensor...
  - No guarantee of safety!
- For realistic flux, need to use ultra high-rate facility upstream.
  - 10<sup>9</sup> protons on target per minute, rather than 10<sup>5</sup>



### 120 GeV protons



## New setup at high-rate area

- Built entirely new setup to support 20 LGADs in high-rate beam
- Hazardous environment..
  - High radiation, frequent SEUs, oxygen deficiency hazard, many barriers to entry





### **Measuring beam intensity**

- No tracker or beam monitor: use LGADs themselves to measure delivered intensity!
- Within 10 millisecond acquisition, count signals in 8 channels.



- Study occupancy across 5x5 sensor: enable alignment to beam.
- Final occupancy: 200M protons / sensor / minute

- x2000 larger flux per sensor than max achieved in regular test beam (slightly less than expectation)



# Aligning to beam

- Study occupancy across sensor w/ 8-ch
- Follow gradient to align sensor



- With best alignment, occupancy in edge pads is 80-90% of center (wide beam)
- Final sensor occupancy: 200M protons / sensor / spill
  - x2000 larger flux per sensor than max achieved in regular test beam (slightly less than expectation)

### Pre-alignment





# Aligning to beam

- Study occupancy across sensor w/ 8-ch
- Follow gradient to align sensor



- With best alignment, occupancy in edge pads is 80-90% of center (wide beam)
- Final sensor occupancy: 200M protons / sensor / spill
  - x2000 larger flux per sensor than max achieved in regular test beam (slightly less than expectation)

Post-alignment





### **Exposure summary**



- Demonstrated safe operation with flux comparable to 1 year in CMS, with 3 proposed thicknesses / vendors!
- Best designed sensors operate happily at safe voltage through full life.
- No longer considered risk to the project!



### Assembling a realistic detector



- Major focus on validation with realistic components and operation modes
  - Performance with ETROC, ETL service hybrids, and DAQ system
- Cooling & mechanical constraints with modules, services routing, mechanical structures





### **ETROC** testing

- ETROC chip: provide ToA and ToT for every hit.
- Achieve 42 ps resolution for LGAD + ETROC1 within specifications!
- 3 detectors aligned in test beam







- $4x4 \rightarrow 16x16$  channels (full size)

# Early prototypes ETROC0 and ETROC1 studied extensively at beam test

Study pairwise combinations to extract single-channel resolutions:  $\sigma_{1/2/3} = 42.0 / 42.7 / 41.3 \text{ ps}$ 

 Next generation ETROC2 submitted Oct. 2022! - CMS-compatible digital interface













## **CMS MTD**

- CMS MTD on track to be first-of-its kind timing detector
- Established mature understanding of LGAD sensors
- Focus now within ETL on validation of full system, and transition towards procurements and production.

## Where do we go next?









# **Timing for future colliders**

- Future collider experiments: pileup only more severe - 1000s of simultaneous collisions: too dense for trackfinding
- Major effort towards "4D tracking" (e.g. 10 ps & 10 micron)



# Precision timing in each tracking layer vastly simplifies pattern recognition



**Snowmass 4D tracking whitepaper** <u>arXiv:2203.13900</u>





# 4D tracking with LGADs

- LGADs— not trivial to miniaturize from millimeter to micron scale
  - Gain layer termination requires  $\geq$  50 micron dead space between channels

2x2 IHEP-IME array









# 4D tracking with LGADs

- LGADs not trivial to miniaturize from millimeter to micron scale
  - Gain layer termination requires  $\geq 50$  micron dead space between channels



- Instead, add AC-coupled electrodes w/ continuous gain region to achieve segmentation: "AC-LGADs"
- Resistive n+ surface layer controls how signals spread across sensor.

# 4D tracking with LGADs



### FNAL test beam setup for AC-LGADs





- Tracking telescope resolution: ~ 5 microns - 4x CMS RD53a pixels (25 x 100 um) + 10x strips (60 microns)
- MCP time ref resolution: 10 ps

- Critical for AC-LGAD characterization:
  - Fine resolution tracker reference
  - Read many channels!

8-channel oscilloscope, 2 GHz, 10 GSa/s Large memory: take 20k events during 4 s spill







# Amplitude ratio between neighbors FNAL 120 GeV proton beam



- Thanks to high gain, obtain resolution much finer than pitch /  $\sqrt{12}$ - In this case: 20-40 microns (and 30 picosecond time resolution!)
- Tuning of n+ resistivity and electrode geometry needed for optimal sharing...

### x [mm]

![](_page_43_Picture_11.jpeg)

# **High resolution AC-LGAD strips**

- Good performance from several BNL 100 to 200 micron strip prototypes
  - Well-tuned signal sharing  $\rightarrow$  uniform 2-strip efficiency  $\rightarrow$  uniform 5-10 um resolution.

![](_page_44_Figure_3.jpeg)

 Promising 4D sensors: 30 ps timing and spatial resolution ~ pitch / 30 2022 JINST 17 P05001 **Fermilab** 

![](_page_44_Figure_7.jpeg)

### Large-area 4D detectors

• Alternate direction: maintain performance with much sparser readout ➡High precision (time & space) with coarser readout & few channels

![](_page_45_Picture_4.jpeg)

### Large-area 4D detectors

- Alternate direction: maintain performance with much sparser readout ➡High precision (time & space) with coarser readout & few channels
- Promising for
  - Electron Ion Collider timing layer: particle ID via time of flight.
  - Space-based power constraints

![](_page_46_Picture_5.jpeg)

![](_page_46_Picture_10.jpeg)

# 2022 large strips campaign

- For realistic application, need to demonstrate large area sensors.
- Extensive campaign to study 15 BNL AC-LGADs in test beam
  - Length 5-25 mm & pitch 500 um (10x longer and 5x coarser than previous sensors)
  - Focus on geometry optimization & tradeoffs with longer sensors.

### 500 um pitch

- 5, 10, 25 mm lengths
- 100, 200, 300 um metal widths

![](_page_47_Figure_8.jpeg)

![](_page_47_Picture_9.jpeg)

Ryan H • Today: preview of results to appear on arXiv soon! 48 11/15/22

# **Gain uniformity**

- New challenge with large area: sensitivity to non-uniformity in gain layer
  - Stripe patterns of high gain observed in most sensors of this production
  - High gain regions limit operating voltage  $\rightarrow$  other regions remain underbiased

![](_page_48_Figure_4.jpeg)

- Expect improved uniformity in next prototypes - Uniform 2x2 cm<sup>2</sup> LGADs for ATLAS/CMS already demonstrated - Still extract useful lessons despite non-uniformity!

# **Spatial resolution**

- Position reconstruction w/ ratio of amplitudes robust against non-uniformity. Achieve 15-20 um resolution for 2-strip events in all 5-10 mm strips - Slight degradation from 1-strip events from within metal, or low gain regions

![](_page_49_Figure_5.jpeg)

Latest production optimized for full 2-hit coverage: 20 um resolution everywhere (pitch / 25!)

Performance for 1 cm strips, 500 um pitch w/100 um metal

![](_page_49_Figure_8.jpeg)

![](_page_50_Figure_0.jpeg)

• > 2 cm: trying few ideas to improve in next beam test.

# **Propagation delays across surface**

• Large electrodes  $\rightarrow$  distant signals arrival with delays O(100 ps) O(100 ps) delays

![](_page_51_Figure_2.jpeg)

- Easily correct for position dependent delays:
  - Trivial within collider tracking system
  - OR, with dual-end readout: self-correcting!

![](_page_51_Picture_6.jpeg)

### Correct with alternating dual-end readout

![](_page_51_Figure_9.jpeg)

![](_page_51_Picture_10.jpeg)

![](_page_51_Picture_12.jpeg)

### **Time resolution**

![](_page_52_Figure_1.jpeg)

- Time resolution ~ 40 ps for 1 cm strips
  - Combining 2 channels & correcting for

![](_page_52_Picture_6.jpeg)

### Conclusions

- Timing capability will be essential in future colliders detectors
  - CMS MTD: first trailblazer
  - 4D trackers to follow in footsteps.
- AC-LGADs can provide excellent 4D performance - 30 ps time resolution and spatial resolution ~20-30x smaller than pitch
- Large, coarse pitch sensors promising
  - 20 microns & 30 picoseconds resolutions in best regions
  - Uniform gain & 2-strip efficiency expected in next prototypes

### Thank you for your attention!

![](_page_53_Picture_12.jpeg)